



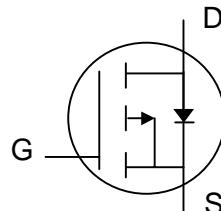
## P-channel Enhancement-mode Power MOSFET

**Simple Drive Requirement**

**Low On-Resistance**

**Fast Switching Performance**

**RoHS-compliant, halogen-free**

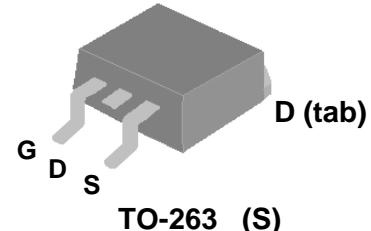


$BV_{DSS}$	-80V
$R_{DS(ON)}$	15mΩ
$I_D$	-95A

## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP9581GS-HF-3 is in the TO-263 package, which is widely used for commercial and industrial surface-mount applications, and is well suited for low voltage applications such as DC/DC converters.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-80	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$ at $T_C=25^\circ\text{C}$	Continuous Drain Current	-95	A
$I_D$ at $T_C=100^\circ\text{C}$	Continuous Drain Current	-60	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-300	A
$P_D$ at $T_C=25^\circ\text{C}$	Total Power Dissipation	250	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	0.5	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient (PCB mount) <sup>3</sup>	40	°C/W

## Ordering Information

AP9581GS-HF-3TR : in RoHS-compliant, halogen-free TO-263, shipped on tape and reel (800 pcs/reel)



**Electrical Specifications at  $T_j=25^\circ\text{C}$  (unless otherwise specified)**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-80	-	-	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-10\text{V}$ , $I_{\text{D}}=-30\text{A}$	-	-	15	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-20\text{A}$	-	-	20	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-1	-	-3	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-10\text{V}$ , $I_{\text{D}}=-30\text{A}$	-	60	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-64\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	-25	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}= \pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=-30\text{A}$ $V_{\text{DS}}=-64\text{V}$	-	72	115	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	11	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge		-	45	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=-40\text{V}$ $I_{\text{D}}=-30\text{A}$ $R_{\text{G}}=3.3\Omega$ $V_{\text{GS}}=-10\text{V}$	-	13	-	ns
$t_r$	Rise Time		-	60	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	135	-	ns
$t_f$	Fall Time		-	165	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$ $V_{\text{DS}}=-25\text{V}$	-	6200	9920	pF
$C_{\text{oss}}$	Output Capacitance		-	900	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	390	-	pF

**Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=-30\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	-1.3	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=-10\text{A}$ , $V_{\text{GS}}=0\text{V}$ , $dI/dt=-100\text{A}/\mu\text{s}$	-	60	-	ns
			-	125	-	nC

1. Pulse width limited by maximum junction temperature.
2. Pulse test
3. Surface mounted on 1in<sup>2</sup> copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.



## Typical Electrical Characteristics

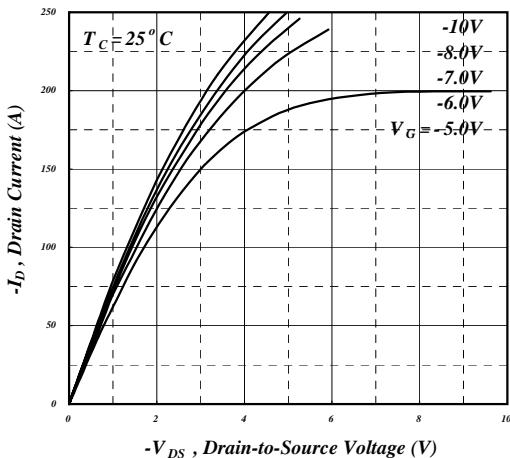


Fig 1. Typical Output Characteristics

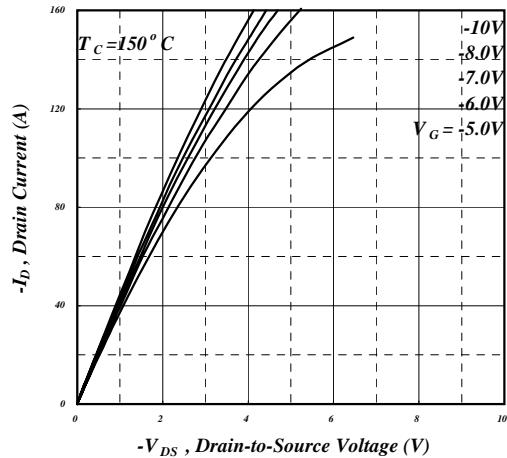


Fig 2. Typical Output Characteristics

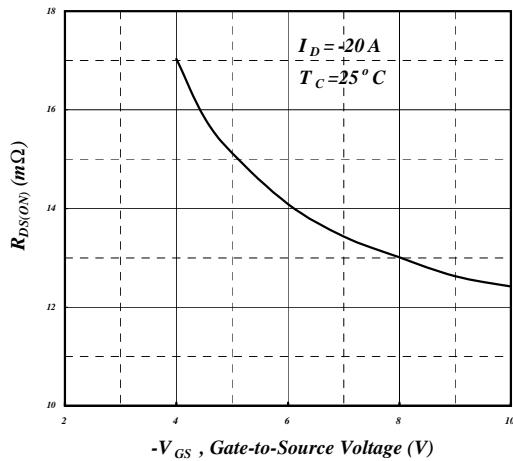


Fig 3. On-Resistance vs. Gate Voltage

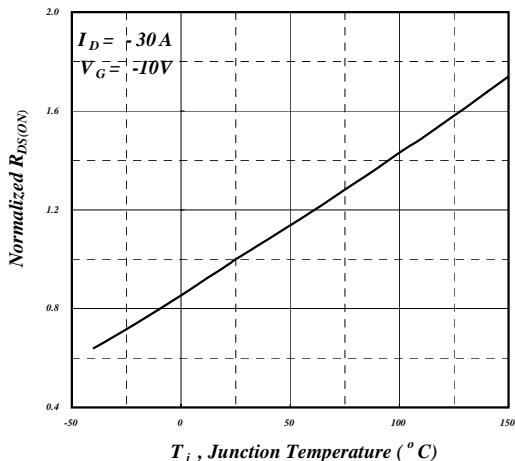


Fig 4. Normalized On-Resistance  
vs. Junction Temperature

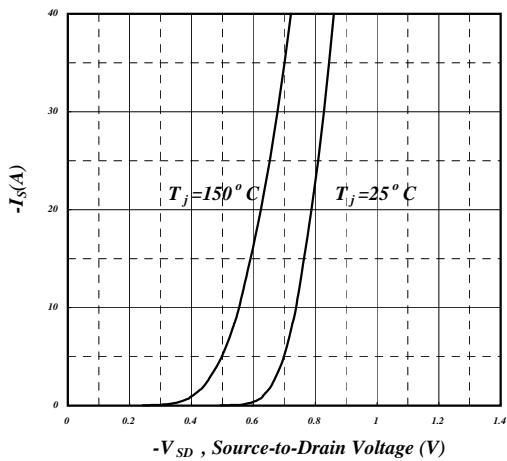


Fig 5. Forward Characteristic of  
Reverse Diode

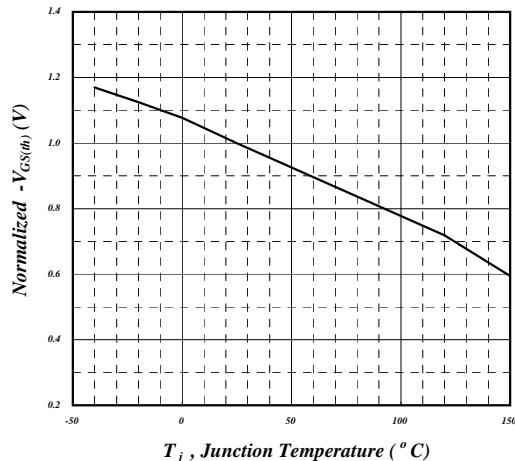


Fig 6. Gate Threshold Voltage vs.  
Junction Temperature



## Typical Electrical Characteristics (cont.)

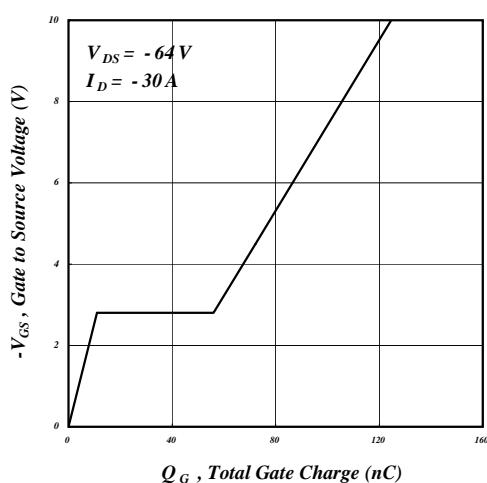


Fig 7. Gate Charge Characteristics

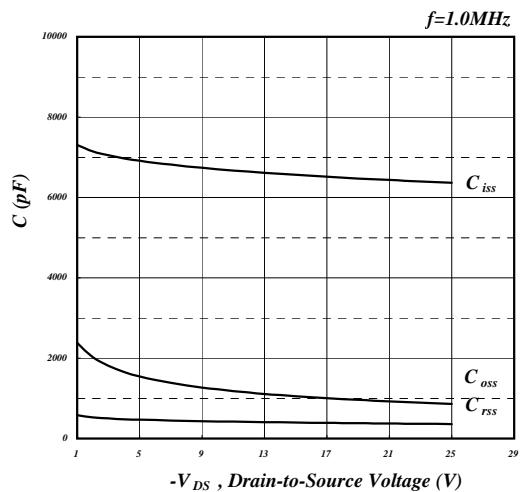


Fig 8. Typical Capacitance Characteristics

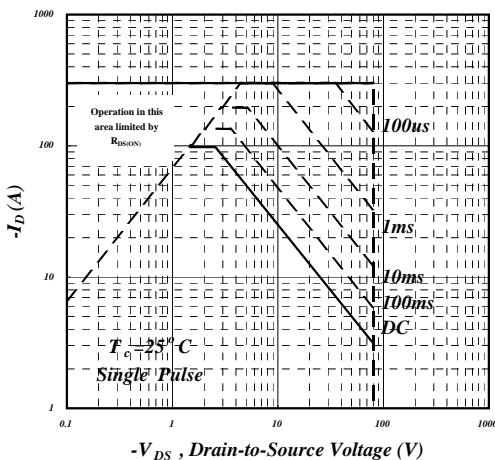


Fig 9. Maximum Safe Operating Area

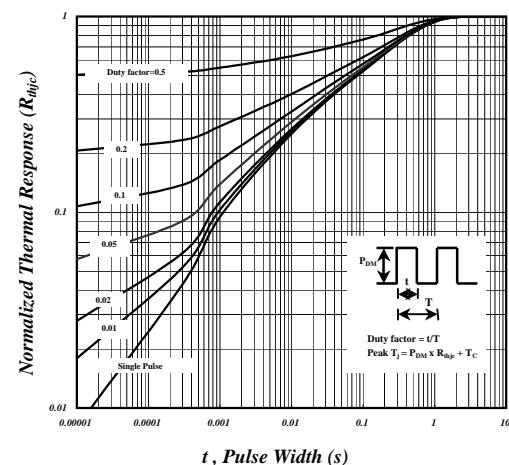


Fig 10. Effective Transient Thermal Impedance

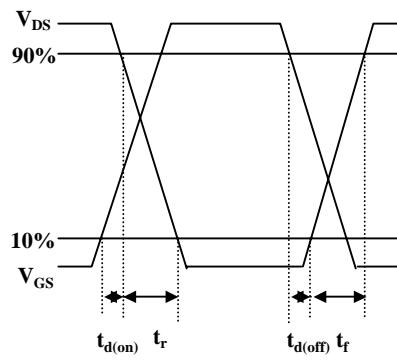


Fig 11. Switching Time Waveform

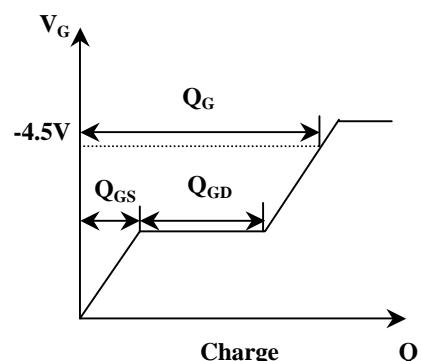
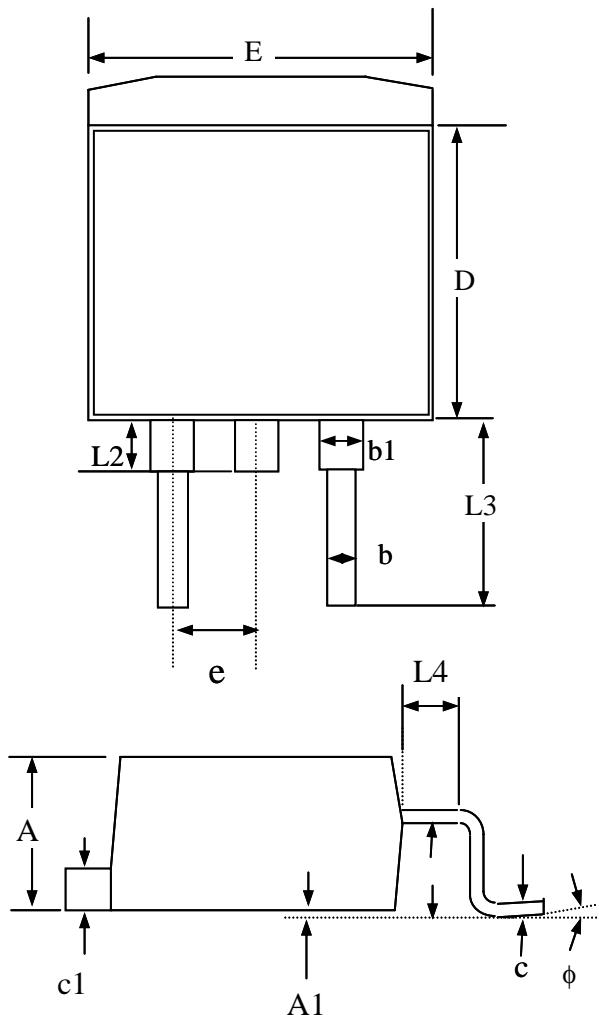


Fig 12. Gate Charge Waveform



### Package Dimensions: TO-263



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	4.25	4.75	5.20
A1	0.00	0.15	0.30
A2	2.20	2.45	2.70
b	0.70	0.90	1.10
b1	1.07	1.27	1.47
c	0.30	0.45	0.60
c1	1.15	1.30	1.45
D	8.30	8.90	9.40
E	9.70	10.10	10.50
e	2.04	2.54	3.04
L2	-----	1.50	-----
L3	4.50	4.90	5.30
L4	-----	1.50	-----

1. All dimensions are in millimeters.
2. Dimensions do not include mold protrusions.

### Marking Information:

